
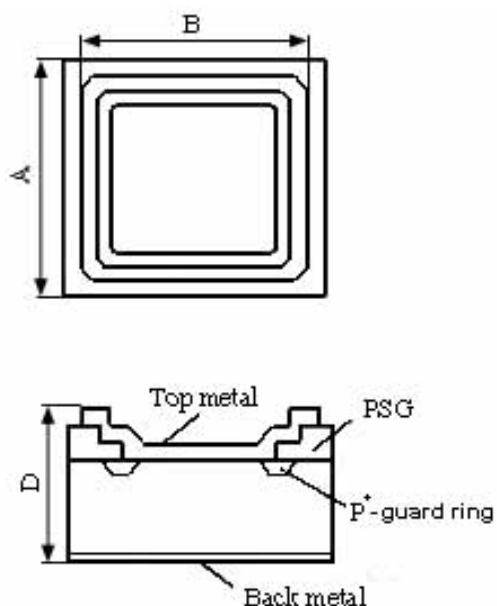


# SCHOTTKY DIODES KDS 2128I. PRELIMINARY



Rev.1. Feb. 2010

|  <b>VSP-MIKRON</b>    | <b>1A/25V. Die Size-51mil.</b> |      |                  |                    |
|--|--------------------------------|------|------------------|--------------------|
| Electrical Characteristics   | Symbol                         | Unit | Spec. limit      | Die Sort           |
| Breakdown Voltage<br>@ $I_R=10mA$  | $V_{BR}$                       | V    | 28               | 30                 |
| Average Rectified Forward Current  | $I_{F(AV)}$                    | A    | 1,0              | -                  |
| DC Forward Voltage<br>@ 25°C, $I_F=1,0A$   | $V_F$                          | V    | 0,33             | 0,32               |
| Maximum Reverse Current<br>@ 25°C, $V_R=25V$<br>25°C, $V_R=28V$<br>100°C, $V_R=25V$                    | $I_R$                          | mA   | 0,6<br>-<br>50,0 | 0,5<br>0,6<br>45,0 |
| Peak Forward Surge Current 8,3ms<br>single half sine-wave superimposed on<br>rated load (JEDEC METHOD) | $I_{FSM}$                      | A    | 60               | -                  |
| Peak Repetitive Reverse Surge Current<br>@2,0µs, f=1kHz., $T_J<125°C$ .                                | $I_{RRM}$                      | A    | 2,0              |                    |
| Electrostatic Discharge Voltage.<br>JEDEC Method. ESD HBM. Contact.                                    | ESD                            | kV   | ±8 (contact)     |                    |
| Voltage Rate of Change   | dV/dt                          | V/µS | 10.000           |                    |
| Operating Junction Temperature   | $T_J$                          | °C   | 125              |                    |



| DIM               | ITEM                | µm           |
|-------------------|---------------------|--------------|
| $A_x$<br>$A_y$    | Wafer Form Die Size | 1300<br>1300 |
| $B_x$<br>$B_y$    | Top Metal Size      | 1112<br>1112 |
| D                 | Thickness           | 300max.      |
| Scribe line Width |                     | 80           |

*Top metal:* a) **Al** – for Wire Bonding;  
b) **Al-Ni-Ag** – for Soldering.  
*Backside metal:* **Ti-Ni-Ag**.